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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



RECEIVED AFTER FINAL  
EXPEDITED PROCEDURE  
JAN 25 2002  
ART UNIT 2813

TECHNOLOGY CENTER 2800  
Docket No. 740756-2064

In re Patent application of: )

Shunpei YAMAZAKI et al. )

Serial No.: 09/437,135 )

Group Art Unit: 2813

Filed: November 10, 1999 )

Examiner: E. Kielin

For: SEMICONDUCTOR DEVICE AND )

METHOD FOR FORMING THE SAME)

**AMENDMENT AFTER FINAL REJECTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Responsive to the Office Action dated **September 17, 2001**, the following amendments and remarks are submitted in connection with the above-identified application.

**IN THE CLAIMS:**

Please amended claims 1, 6, 11, 30, and 34 as follows. Attached hereto is a marked up copy of the claims in their amended form.

1. (Thrice Amended) A method for manufacturing a semiconductor device comprising the steps of:

forming a semiconductor film comprising amorphous silicon over a substrate;

crystallizing said semiconductor film by irradiating a laser light;

patterning the crystallized semiconductor film to form first and second semiconductor islands;

forming an insulating film on each of said first and second semiconductor islands by a vapor phase deposition;